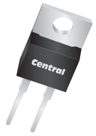
Material Composition Specification

TO-220-2 Case

Central Semiconductor Corp.



Device average mass . . . . **1.95 g**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material (%wt)	Material (mg)	Substance	CAS No.	Substance (%wt)	Substance (mg)	Substance (ppm)
active device	doped SiC	0.38%	7.5	SiC	409-21-2	0.38%	7.5	3,846
bond wire	aluminum	0.13%	2.5	Al	7429-90-5	0.13%	2.5	1,282
leadframe	Cu alloy	67.7%	1,320.1	Cu	7440-50-8	67.59%	1,318	675,897
				Fe	7439-89-6	0.01%	0.1	51
				P	7723-14-0	0.1%	2.0	1,026
die attach	high temperature solder	0.3%	5.9	Pb	7439-92-1	0.28%	5.46	2,800
				Sn	7440-31-5	0.01%	0.29	149
				Ag	7440-22-4	0.01%	0.15	77
encapsulation*	EMC GREEN	30.77%	600	silica	7631-86-9	23.08%	450	230,769
				epoxy resin	Proprietary	4.77%	93	47,692
				epoxy polymer	Proprietary	2.31%	45	23,077
				Sb_2O_3	1309-64-4	0.52%	10.2	5,231
				carbon black	1333-86-4	0.09%	1.8	923
plating	matte tin	0.72%	14	Sn	7440-31-5	0.72%	14	7,179

*EMC GREEN molding compound is Halogen-Free.

R0 (6-May 2013)